RELIABILITY REPORT

FOR

MAX4008EUT+
(MAX4007)

PLASTIC ENCAPSULATED DEVICES

November 3, 2008

MAXIM INTEGRATED PRODUCTS

120 SAN GABRIEL DR.

SUNNYVALE, CA 94086

Approved by
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Quality Assurance
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Conclusion

The MAX4008EUT+ successfully meets the quality and reliability standards required of all Maxim products. In addition, Maxim"s continuous reliability monitoring program ensures that all outgoing product will continue to meet Maxim"s quality and reliability standards.

Table of Contents

I. Device Description

A. General

The MAX4007/MAX4008 precision, high-side, high-voltage current monitors are specifically designed for monitoring photodiode current in fiber applications. They offer a connection point for the reference current and a monitor output that produces a signal proportional to the reference current. The monitor output of the MAX4007 is a current proportional to the reference current. The monitor output of the MAX4008 is a voltage proportional to the reference current. The current monitors have six decades of dynamic range and monitor reference currents of 250nA to 2.5mA with better than 5% accuracy. The photodiode current can be monitored from 10nA to 10mA with reduced accuracy. The MAX4007/MAX4008 accept a supply voltage of +2.7V to +76V, suitable for APD or PIN photodiode applications. Internal current limiting (20mA, typ) protects the devices against short circuit to ground. A clamp diode protects the monitor output from overvoltage. Additionally, these devices feature thermal shutdown if the die temperature reaches +150°C. The MAX4007/MAX4008 are available in tiny, spacesaving 6-pin SOT23 packages, and operate over the extended temperature range of -40°C to +85°C.

II. Manufacturing Information

A. Description/Function:	High-Accuracy, 76V, High-Side Current Monitors in SOT23
B. Process:	BCD8
C. Number of Device Transistors:	
D. Fabrication Location:	Oregon
E. Assembly Location:	UTL Thailand
F. Date of Initial Production:	January 25, 2003

III. Packaging Information

A. Package Type:	6-pin SOT23
B. Lead Frame:	Cu Alloy
C. Lead Finish:	100% matte Tin
D. Die Attach:	Conductive Epoxy
E. Bondwire:	Au (1.0 mil dia.)
F. Mold Material:	Epoxy with silica filler
G. Assembly Diagram:	#
H. Flammability Rating:	Class UL94-V0
I. Classification of Moisture Sensitivity per JEDEC standard J-STD-020-C	Level 1
J. Single Layer Theta Jb:	115*°C/W
K. Single Layer Theta Jc:	80°C/W
L. Multi Layer Theta Ja:	74.6°C/W
M. Multi Layer Theta Jc:	6.1°C/W

IV. Die Information

A. Dimensions:	60 X 41 mils
B. Passivation:	Si_3N_4/SiO_2 (Silicon nitride/ Silicon dioxide
C. Interconnect:	Aluminum/Si (Si = 1%)
D. Backside Metallization:	None
E. Minimum Metal Width:	3.0 microns (as drawn)
F. Minimum Metal Spacing:	3.0 microns (as drawn)
G. Bondpad Dimensions:	5 mil. Sq.
H. Isolation Dielectric:	SiO_2
I. Die Separation Method:	Wafer Saw

V. Quality Assurance Information

A. Quality Assurance Contacts:	Ken Wendel (Director, Reliability Engineering) Bryan Preeshl (Managing Director of QA)
B. Outgoing Inspection Level:	0.1% for all electrical parameters guaranteed by the Datasheet. 0.1% For all Visual Defects.
C. Observed Outgoing Defect Rate:	< 50 ppm
D. Sampling Plan:	Mil-Std-105D

VI. Reliability Evaluation

A. Accelerated Life Test

The results of the 135°C biased (static) life test are pending. Using these results, the Failure Rate (λ) is calculated as follows:

$$\lambda = \frac{1}{MTTF} = \frac{1.83}{192 \times 4340 \times 48 \times 2}$$ (Chi square value for MTTF upper limit)

(where 4340 = Temperature Acceleration factor assuming an activation energy of 0.8eV)

$\lambda = 22.4 \times 10^{-9}$

$\lambda = 22.4$ F.I.T. (60% confidence level @ 25°C)

The following failure rate represents data collected from Maxim's reliability monitor program. Maxim performs quarterly 1000 hour life test monitors on its processes. This data is published in the Product Reliability Report found at http://www.maxim-ic.com/. Current monitor data for the BCD8 Process results in a FIT Rate of 2.3 @ 25C and 39.6 @ 55C (0.8 eV, 60% UCL)

B. Moisture Resistance Tests

The industry standard 85°C/85%RH or HAST testing is monitored per device process once a quarter.

C. E.S.D. and Latch-Up Testing

The OY13 die type has been found to have all pins able to withstand a HBM transient pulse of 2000 per Mil-Std 883 Method 3015.7. Latch-Up testing has shown that this device withstands a current of 250 mA.

Table 1
Reliability Evaluation Test Results

MAX4008EUT+

TEST ITEM	TEST CONDITION	FAILURE IDENTIFICATION	SAMPLE SIZE	NUMBER OF FAILURES
Static Life Test (Note 1)				
	Ta = 135°C Biased Time = 192 hrs.	DC Parameters & functionality	48	0
Moisture Testing (Note 2)				
85/85	Ta = 85°C RH = 85% Biased Time = 1000hrs.	DC Parameters & functionality	77	0
Mechanical Stress (Note 2)				
Temperature Cycle	-65°C/150°C 1000 Cycles Method 1010	DC Parameters & functionality	77	0

Note 1: Life Test Data may represent plastic DIP qualification lots.
Note 2: Generic Package/Process data